

Chip packaging apparatus and method thereofAbstract of Disclosure

Disclosed is a chip packaging apparatus. The chip packaging apparatus comprises: at least one chip supplying device; at least one chip processing device configured to process a chip supplied by a corresponding chip supplying device; and at least one chip transferring device, wherein each chip transferring device has a plurality of bonding heads, and each of the bonding heads is used to transfer one chip processed by a corresponding chip processing device. Each chip processing device comprises at least two pick-up platforms, each of the pick-up platforms is configured such that multiple chips can be simultaneously provided thereon, and the plurality of bonding heads on a corresponding chip transferring device is configured to simultaneously pick up multiple chips from each pick-up platform in one operation. A method for packaging chips is also disclosed.